

WAFER GRINDING METHOD AND WAFER GRINDING MACHINE

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ABSTRACT OF THE DISCLOSURE

10 A wafer grinding method and a wafer grinding machine
are disclosed for grinding a wafer by executing both the
rough grinding process and the finish grinding process.
After the rough grinding process before the finish
grinding process, the wafer thickness is measured with a
noncontact-type thickness gauge, and during the finish
grinding process, the finish thickness is finely adjusted
15 by use of a contact-type thickness gauge and referring to
the measurement data of the noncontact-type thickness
gauge.

Figure 1